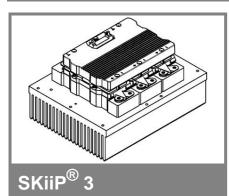
SKiiP 1513GB122-3DL



2-pack-integrated intelligent Power System

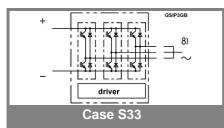
Power Section

SKiiP 1513GB122-3DL

Data

Power section features

- SKiiP technology inside
- SPT (Soft Punch Trough) IGBTs
- CAL diode technology
- Integrated current sensor
- Integrated temperature sensor
- Integrated heat sink
- IEC 60721-3-3 (humidity) class 3K3/IE32 (SKiiP[®] 3 System)
- IEC 60068-1 (climate) 40/125/56
- UL recognized File no. E63532
- with assembly of suitable MKP capacitor per terminal
- AC connection busbars must be connected by the user; copper busbars available on request



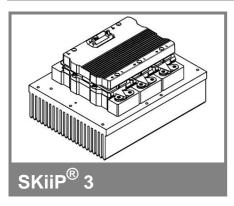
| Absolute | Maximum Ratings | Γ_s = 25 °C unless otherwise specified | | | | | | |
|--------------------------------------|--|---|-------|--|--|--|--|--|
| Symbol Conditions | | Values | Units | | | | | |
| IGBT | | | | | | | | |
| V _{CES} | | 1200 | V | | | | | |
| V _{CC} ¹⁾ | Operating DC link voltage | 900 | V | | | | | |
| V _{GES} | | ± 20 | V | | | | | |
| Ι _C | T _s = 25 (70) °C | 1500 (1125) | А | | | | | |
| Inverse o | Inverse diode | | | | | | | |
| $I_F = -I_C$ | T _s = 25 (70) °C | 1340 (1020) | А | | | | | |
| I _{FSM} | T _j = 150 °C, t _p = 10 ms; sin | 10200 | A | | | | | |
| I²t (Diode) | Diode, T _j = 150 °C, 10 ms | 520 | kA²s | | | | | |
| T _j , (T _{stg}) | | - 40 + 150 (125) | °C | | | | | |
| V _{isol} | rms, AC, 1 min, main terminals to heat sink | 3000 | V | | | | | |
| I _{AC-terminal} | per AC terminal, rms, T _s = 70 °C, | 400 | А | | | | | |
| | T _{terminal} <115 °C | | | | | | | |

| Characteristics $T_s = 25 \degree C$ unless otherwise spectrum $T_s = 25 \degree C$ unl | | | | | | |
|--|--|------|------------|-----------|-------|--|
| Symbol Conditions | | min. | typ. | max. | Units | |
| IGBT | | | | | | |
| V _{CEsat} | I_{C} = 900 A, T_{j} = 25 (125) °C; measured at terminal | | 2,3 (2,5) | 2,6 | V | |
| V _{CEO} | T _i = 25 (125) °C; at terminal | | 1,1 (1) | 1,3 (1,2) | v | |
| r _{CE} | T _i = 25 (125) °C; at terminal | | 1,3 (1,7) | 1,5 (1,9) | mΩ | |
| I _{CES} | $V_{GE} = 0 V, V_{CE} = V_{CES},$ T _i = 25 (125) °C | | 3,6 (108) | | mA | |
| E _{on} + E _{off} | I _C = 900 A, V _{CC} = 600 V | | 270 | | mJ | |
| | T _j = 125 °C, V _{CC} = 900 V | | 476 | | mJ | |
| R _{CC+EE} | terminal chip, T _i = 25 °C | | 0,17 | | mΩ | |
| L _{CE} | top, bottom | | 4 | | nH | |
| C _{CHC} | per phase, AC-side | | 5,1 | | nF | |
| Inverse | diode | | | | • | |
| $V_F = V_{EC}$ | $I_F = 900 \text{ A}, T_j = 25 (125) ^{\circ}\text{C}$ measured at terminal | | 1,95 (1,7) | 2,1 | V | |
| V _{TO} | T _i = 25 (125) °C | | 1,1 (0,8) | 1,2 (0,9) | V | |
| r _T | T _i = 25 (125) °C | | 0,9 (1) | 1 (1,2) | mΩ | |
| E _{rr} | I _C = 900 A, V _{CC} = 600 V | | 72 | | mJ | |
| | T _j = 125 °C, V _{CC} = 900 V | | 92 | | mJ | |
| Mechan | ical data | | | | • | |
| M _{dc} | DC terminals, SI Units | 6 | | 8 | Nm | |
| M _{ac} | AC terminals, SI Units | 13 | | 15 | Nm | |
| w | SKiiP [®] 3 System w/o heat sink | | 2,4 | | kg | |
| w | heat sink | | 7,5 | | kg | |
| Thermal characteristics (PX 16 heat sink with fan SKF 16B-230-1); "s" reference to heat sink; "r" reference to built-in temperature sensor (acc. IEC 60747-15) | | | | | | |
| R _{th(j-s)l} | per IGBT | | | 0,02 | K/W | |
| | | | | | | |

| R _{th(j-s)I} | per IGB | Т | | | | | 0,02 | K/W | |
|-----------------------|----------------------|-------------------------------------|-----|-----|-----|----------------------|-------|------|--|
| R _{th(j-s)D} | per diod | е | | | | | 0,038 | K/W | |
| Z _{th} | R _i (mK/V | R _i (mK/W) (max. values) | | | | tau _i (s) | | | |
| | 1 | 2 | 3 | 4 | 1 | 2 | 3 | 4 | |
| Z _{th(j-r)I} | 3,4 | 9,6 | 7 | 0 | 363 | 0,18 | 0,04 | 1 | |
| Z _{th(j-r)D} | 12 | 12 | 18 | 20 | 30 | 5 | 0,25 | 0,04 | |
| Z _{th(r-a)} | 2,1 | 20 | 5,5 | 1,4 | 210 | 85 | 11 | 0,4 | |

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SKiiP 1513GB122-3DL



2-pack-integrated intelligent Power System

2-pack integrated gate driver SKiiP 1513GB122-3DL

Data

Gate driver features

- CMOS compatible inputs
- Wide range power supply
- Integrated circuitry to sense phase current, heat sink temperature and DC-bus voltage (option)
- Short circuit protection
- Over current protection
- Over voltage protection (option)
- Power supply protection against under voltage
- Interlock of top/bottom switch
- Isolation by transformers
- Fibre optic interface (option for GB-types only)
- IEC 60068-1 (climate) 40/85/56
- UL recognized file no. 242581

| Absolute | Maximum Ratings | a = 25 °C unless otherwise specified | | |
|-------------------------------------|---|--------------------------------------|-------|--|
| Symbol | Conditions | Values | Units | |
| V _{S2} | unstabilized 24 V power supply | 30 | V | |
| V _i | input signal voltage (high) | 15 + 0,3 | V | |
| dv/dt | secondary to primary side | 75 | kV/µs | |
| V _{isollO} | input / output (AC, rms, 2) | 3000 | V | |
| VisoIPD | partial discharge extinction voltage, rms, $Q_{PD} \leq 10 \text{ pC}$; | 1170 | V | |
| V _{isol12} | output 1 / output 2 (AC, rms, 2 s) | 1500 | V | |
| f _{sw} | switching frequency | 10 | kHz | |
| f _{out} | output frequency for I _{peak(1)} =I _C | 10 | kHz | |
| T _{op} (T _{stg}) | operating / storage temperature | - 40 + 85 | °C | |

| Characte | eristics | (T _a | | | = 25 °C) |
|------------------------|--|-----------------|-------------------|--------------------------------------|----------|
| Symbol | Conditions | min. | typ. | max. | Units |
| V _{S2} | supply voltage non stabilized | 13 | 24 | 30 | V |
| I _{S2} | V _{S2} = 24 V | 278+29*f/ | /kHz+0,0001 | 15*(I _{AC} /A) ² | mA |
| V _{iT+} | input threshold voltage (High) | | | 12,3 | V |
| V _{iT-} | input threshold voltage (Low) | 4,6 | | | V |
| R _{IN} | input resistance | | 10 | | kΩ |
| CIN | input capacitance | | 1 | | nF |
| t _{d(on)IO} | input-output turn-on propagation time | | 1,3 | | μs |
| t _{d(off)IO} | input-output turn-off propagation time | | 1,3 | | μs |
| t _{pERRRESET} | error memory reset time | | 9 | | μs |
| t _{TD} | top / bottom switch interlock time | | 3,3 | | μs |
| I _{analogOUT} | max. 5mA; 8 V corresponds to 15 V supply voltage for external components | | 1500 | | A |
| I _{s1out} | max. load current | | | 50 | mA |
| I _{TRIPSC} | over current trip level | | | | |
| | $(I_{analog} OUT = 10 V)$ | | 1875 | | А |
| T _{tp} | over temperature protection | 110 | | 120 | °C |
| UDCTRIP | U _{DC} -protection (U _{analog OUT} = 9 V); | | not implemente | d | V |
| | (option for GB types) | | | | |

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